

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6679124

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
RICHARD T. CHEN	06/26/2017
WILL J. TAN	06/20/2017
RECEIVING PARTY DATA	
Name:	MICROFABRICA INC.
Street Address:	7911 HASKELL AVENUE
City:	VAN NUYS
State/Country:	CALIFORNIA
Postal Code:	91406
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17174218
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NAME OF SUBMITTER:	DENNIS R. SMALLEY
SIGNATURE:	/Dennis R. Smalley/
DATE SIGNED:	04/27/2021
Total Attachments: 2	
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ASSIGNMENT – MULTIPLE INVENTORS – ALL INVENTIONS COMMONLY OWNED

For good and valuable consideration, receipt of which is hereby acknowledged, we

Name	Mailing Address	Residence City and State
Richard T. Chen	7911 Haskell Avenue, Van Nuys, CA 91406	Stevenson Ranch, CA
Will J. Tan	7911 Haskell Avenue, Van Nuys, CA 91406	Pasadena, CA

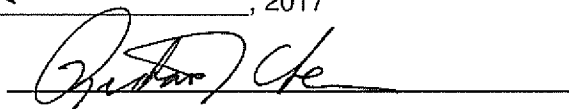
hereby sell, assign and transfer to Microfabrica Inc. having a place of business at 7911 Haskell Avenue, Van Nuys, California 91406, its successors, and assigns, the entire right, title, and interest throughout the world to the inventions that we have invented or co-invented, though possibly not claimed, as set forth in the following patent(s) and/or patent application(s)

Country	Patent or App. No.	Issue Date or Filing Date	Title
US	App. No. 15/283,013	Filed: September 30, 2016	Micro Heat Transfer Arrays, Micro Cold Plates, and Thermal Management Systems for Cooling Semiconductor Devices, and Methods for Using and Making Such Arrays, Plates, and Systems

and for all other patent applications and patents of every country for said inventions (whether or not yet filed), including divisions, reissues, continuations, and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for other patents in the United States and/or foreign countries for said inventions, and to claim all rights of priority without further authorization from me; we agree to execute all papers useful in connection with these patent applications and/or patents, and generally to do everything possible to aid said assignee, their successors, assigns, and nominees, at their request and expense, in obtaining and enforcing patents for said inventions in all countries; and we request that the United States Patent and Trademark Office and all other patent granting authorities to issue all patents granted for said inventions to the above-named assignee, its successors, and assigns.

First Inventor

Executed this 26 day of June, 2017



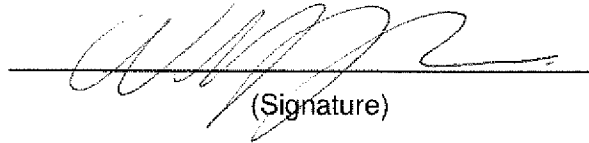
(Signature)

Richard T. Chen

Name (Typed or Printed)

Second Inventor

Executed this 20 day of June, 2017



(Signature)

Will J. Tan

Name (Typed or Printed)